

EAST Search History

S3	43	S2 and (((heat or thermal or temperature) near5 sensitive) near5 (component or (circuit adj board)or "SMD" or "THT"))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/12/11 03:40
S4	9	("3649942" "4477857" "4652848" "5097247" "5586014" "5708553" "5712610" "6198376" "6232868").PN. OR ("6734781").URPN.	US-PGP UB; USPAT; USOCR	OR	ON	2007/12/11 03:37
S5	179	29/838.ccls.	US-PGP UB; USPAT; USOCR	OR	ON	2007/12/11 03:44
S6	1799	29/840.ccls.	US-PGP UB; USPAT; USOCR	OR	ON	2007/12/11 03:48
S7	151	S6 and (solder\$3 near5 (melt\$3 or reflow\$3) near5 (furnace or oven))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/12/11 03:49
S8	2107	(29/825,837).ccls.	US-PGP UB; USPAT; USOCR	OR	ON	2007/12/11 03:51
S9	36	S8 and (solder\$3 near5 (melt\$3 or reflow\$3) near5 (furnace or oven))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/12/11 03:50

EAST Search History

S10	390	228/214.ccls.	US-PGP UB; USPAT; USOCR	OR	ON	2007/12/11 03:51
S11	266	S1 and conveyor	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/12/11 03:56
S12	171	S11 and (shield\$3 or mask\$3 or cover\$3)	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/12/11 04:10
S13	5	("4515304" "4761881" "50 70604" "5785233" "61232 47").PN.	USPAT	OR	ON	2007/12/11 04:11
S14	64	("3832769" "4051550" "4139881" "4196839" "4215025" "4373259" "4506443" "4515304" "4642889").PN. OR ("4761881").URPN.	US-PGP UB; USPAT; USOCR	OR	ON	2007/12/11 04:12
S15	16	("3710069" "4651401" "5141147" "5163599" "5345061" "5433368" "5515605" "5785233" "5842627" "5993500"). PN. OR ("6123247"). URPN.	US-PGP UB; USPAT; USOCR	OR	ON	2007/12/11 04:12

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	5	((solder\$3 or braz\$3) near5 (((double near2 sided) or ((first near2 second) near5 (side or surface)) or top or bottom) near5 (board or substrate)) near5 shield near5 (reflow\$3 or wave))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/23 11:31
L5	18	((solder\$3 or braz\$3) with (((double near2 sided) or ((first near2 second) near5 (side or surface)) or top or bottom) with (board or substrate)) with shield with (reflow\$3 or wave))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/23 11:38
L6	15	((solder\$3 or braz\$3) with (((double near2 sided) or ((first near2 second) near5 (side or surface)) or top or bottom) with (board or substrate)) with (shield with heat))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/23 11:43
L7	54	((solder\$3 or braz\$3) near2 ((wired adj component) or "THT"))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/23 12:23

EAST Search History

L8	4	7 and shield	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/23 12:24
L9	172	((solder\$3 or braz\$3) adj ("SMD" or (wired adj component) or "THT"))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/23 12:57
L10	11	9 and (reflow\$3 adj oven)	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/23 12:58
S1	1520	(solder\$3 near5 reflow\$3 near5 oven)	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/12/11 03:56
S2	4501	(solder\$3 near5 (melt\$3 or reflow\$3) near5 (furnace or oven))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/12/11 03:44

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	3642	((solder\$3 or Reflow\$3) near5 ((wired adj (lead or component)) or "SMD" or "THT" or "THF" or pin or wire) near5 (dress\$3 or bent or bend\$3 or cut\$4 or crimp\$3 or clinch\$3 or shorten\$3))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/25 07:27
L3	69	((solder\$3 or Reflow\$3) adj ((wired adj (lead or component)) or "SMD" or "THT" or "THF" or pin or wire) adj (dress\$3 or bent or bend\$3 or cut\$4 or crimp\$3 or clinch\$3 or shorten\$3))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/25 07:28
L4	160	2 and (via near5 (hole or opening))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/25 07:45
L5	7	((solder\$3 or Reflow\$3) near5 ((lead or component) or "SMD" or "THT" or "THF") near5 (pin wire) near5 (board near5 hole) near5 (dress\$3 or bent or bend\$3 or cut\$4 or crimp\$3 or clinch\$3 or shorten\$3))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/25 07:53

EAST Search History

L8	18	((solder\$3 or Reflow\$3) with (component near5 (pin or wire) with (board near5 hole) with (dress\$3 or bent or bend\$3 or cut\$4 or crimp\$3 or clinch\$3 or shorten\$3)))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/25 08:08
L14	57	(5 or 6 or 7 or 8 or 9 or 10 or 11) and (attach\$3 or mechanical or mechanically)	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/25 08:28
L17	22	(5 or 6 or 7 or 8 or 9 or 10 or 11) and ((attach\$3 or secur\$3) near5 (glue or adhesive or mechanical or mechanically or fasten\$3 or clamp\$4 or hold\$3))	US-PGP UB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/25 08:33